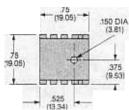
HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

Horizontally mounted, light-weight, low-cost heat dissipators

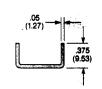
- Accommodates all flat plastic case power semiconductors.
- Efficient design requires just .71 sq. in. of board area (PA Series) and .31" to .5" height above board.
- Larger PB Series offers greater heat dissipation, additional hole patterns, and dual semiconductor mounting capability.
- Only one mounting screw required to secure dissipators to semiconductor and
- circuit board.
- Most effective heat dissipator in performance/unit cost.

PC1-1CB

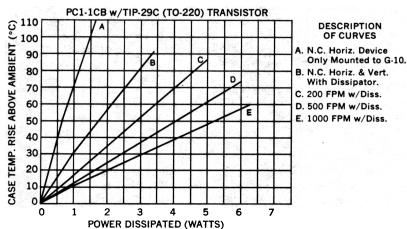








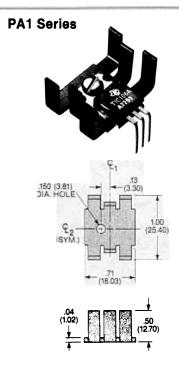
Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



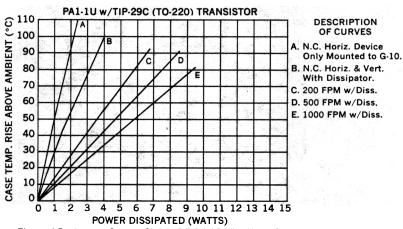
- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 2.4 °C/watt for unplated part in natural convection only.

Ordering Information

IERC PART NO.				Max.
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Semiconductor Accommodated	Weight (Grams)
PC1-1U	PC1-10B	PC1-1B	T0-126, T0-127, T0-220	1,9



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Uprate 2.4 °C/watt for black part in natural convection only.
 Derate 0.6 °C/watt for Insulube® part in natural convection only.

Ordering Information

	IERC PA		Max.		
Unplated	Com'l. Black Anodize	Mil. Black Anodize	Insulube® 448	Semiconductor Accommodated	Weight (Grams)
PA1U PA1-1U	PA1CB PA1-1CB	PA1B PA1-1B	PA1 PA1-1	Undrilled TO-126, TO-127, TO-220	2.0 2.0

Note: See page iv for other finishes.